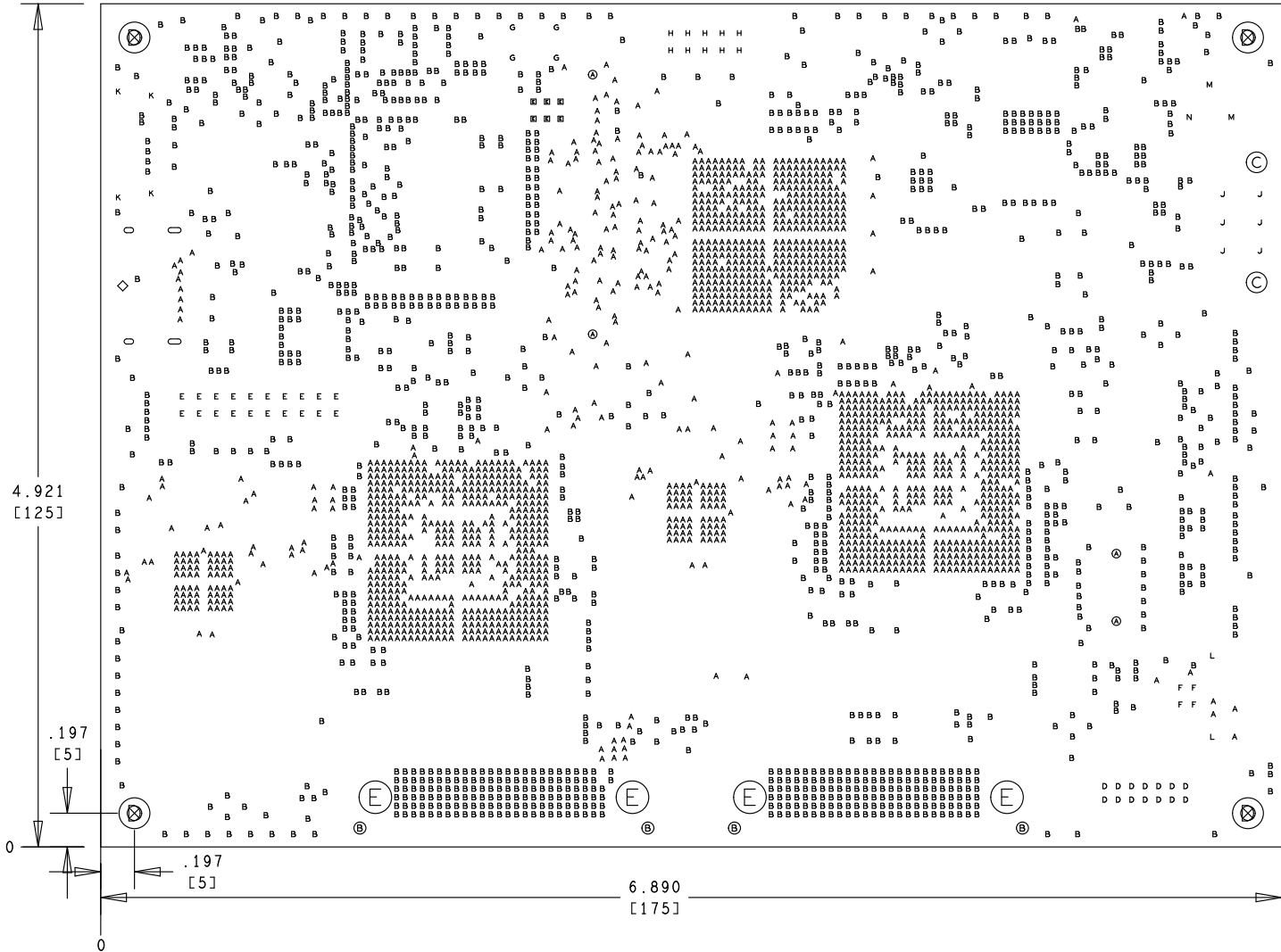


LAYER STACK-UP - ALL DIMENSIONS IN INCHES				
		50ohm SINGLE ENDED IMPEDANCE CONTROL +/- 10%	90ohm DIFFERENTIAL IMPEDANCE CONTROL +/- 10%	100ohm DIFFERENTIAL IMPEDANCE CONTROL +/- 10%
LAYER#	COPPER WEIGHT (OZ)	TRACE WIDTH	TRACE WIDTH / SPACE	TRACE WIDTH / SPACE
LAYER 1 - PRIMARY SIDE - SIGNAL	HALF+PLATING	0.0068	0.0055/0.0055	0.00475/ 0.00725
LAYER 2 - GROUND PLANE	H			
LAYER 3 - SIGNAL	H	0.0057	0.0054/0.0056	0.00475/ 0.00725
LAYER 4 - GROUND PLANE	H			
LAYER 5 - SIGNAL	H	0.0057	0.0054/0.0056	0.00475/ 0.00725
LAYER 6 - GROUND PLANE	H			
LAYER 7 - SPLIT POWER PLANE	H			
LAYER 8 - SPLIT POWER PLANE	H			
LAYER 9 - GROUND PLANE	H			
LAYER 10 -SIGNAL	H	0.0057	0.0054/0.0056	0.00475/ 0.00725
LAYER 11 -GROUND PLANE	H			
LAYER 12 -SIGNAL	H	0.0057	0.0054/0.0056	0.00475/ 0.00725
LAYER 13 -GROUND PLANE	H			
LAYER 14- SECONDARY SIDE - SIGNAL	HALF+PLATING	0.0068	0.0055/0.0055	0.00475/ 0.00725

DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
A	10.0	+0.0/-10.0	PLATED	1872
B	12.0	+3.0/-3.0	PLATED	1393
D	28.0	+3.0/-3.0	PLATED	14
E	35.0	+3.0/-3.0	PLATED	20
B	35.0	+3.0/-3.0	PLATED	6
F	36.0	+3.0/-3.0	PLATED	4
G	40.0	+3.0/-3.0	PLATED	4
H	45.0	+3.0/-3.0	PLATED	10
J	50.0	+3.0/-3.0	PLATED	6
K	51.0	+3.0/-3.0	PLATED	4
L	90.0	+3.0/-3.0	PLATED	2
M	120.0	+3.0/-3.0	PLATED	2
N	140.0	+3.0/-3.0	PLATED	1
⊙	40.0	+3.0/-3.0	NON-PLATED	4
◇	58.0	+3.0/-3.0	NON-PLATED	1
⊗	66.0	+3.0/-3.0	NON-PLATED	4
⊙	118.0	+3.0/-3.0	NON-PLATED	2
⊙	180.0	+3.0/-3.0	NON-PLATED	4
⊙	182.0	+3.0/-3.0	NON-PLATED	4
○	55.0x30.0	+3.0/-3.0	PLATED	2
○	75.0x30.0	+3.0/-3.0	PLATED	2



CUSTOMER NAME		TEXAS INSTRUMENTS			
BOARD NAME		DLPLCRC900DEVM		DESCRIPTION	
		DRILL DRAWING			
BOARD NO.	2513535	REV	G	DATE	25 SEP 2020
		PRJ#		SH	21 OF 21

- FAB NOTES:
- ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE NOTED. ALL BOARD OUTLINE DIMENSION TOLERANCES ARE +/- .010".
 - THE PWB SHALL BE FABRICATED TO IPC-6012, CLASS 2 AND WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2. CURRENT REVISIONS.
 - BOARD MATERIAL SHALL BE 180 Tg/350 Td ISOLA FR-370HR OR EQUIVALENT, RoHS COMPLIANT AND LEAD FREE ASSEMBLY CAPABLE. BOARD MATERIAL SHALL MEET OR EXCEED IPC-4101B. COLOR: NATURAL.
 - BOARD MATERIAL & CONSTRUCTION TO BE U.L. APPROVED AND MARKED ON THE FINISHED BOARD. PCB AND PLASTIC ENCLOSURES SHALL BE UL-RECOGNIZED 94-0.
 - MINIMUM COPPER WALL THICKNESS OF PLATED-THRU HOLES TO BE .001 INCH, WITH A MINIMUM ANNULAR RING OF .001 INCH.
 - OVERALL BOARD THICKNESS TO BE .090 +/- 10% AND APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES, MEASURED FROM COPPER TO COPPER.
 - MAX. WARP & TWIST TO BE .0075 INCHES PER INCH.
 - BOARD MUST BE ELECTRICALLY TESTED USING SUPPLIED IPC-D-356 NETLIST.
 - PLATED THROUGH SLOT INDICATED WITH MULTIPLE DRILL HITS SHOULD BE FINISHED AS SMOOTH WALL BY VENDOR.
 - FABRICATOR SHOULD REMOVE ANY UNUSED PADS ON INTERNAL LAYERS.
- PROCESS NOTES:
- EXCEPT AS NOTED BELOW, PLATE ALL EXPOSED AREAS WITH ELECTROLESS IMMERSION GOLD, FLASH GOLD PROCESS IS ALSO ACCEPTABLE. REQUIRED PLATING THICKNESS: NICKEL 150 MICROINCHES MIN GOLD 5-15 MICROINCHES THK MIN.
 - PLATE ALL THE PAD AREAS OF J18 AND J19, TOP SIDE, WITH A MINIMUM OF 35 AND MAXIMUM 50 MICRO-INCHES OF ELECTROLYTIC HARD GOLD OVER A MINIMUM OF 100 MICRO-INCHES OF ELECTROLYTIC NICKEL.
 - IMPEDANCE INFO IS PROVIDED FOR ALL ROUTING LAYERS BUT SOME LAYERS DO NOT HAVE EVERY LISTED TRACE WIDTH.
 - TRACE WIDTHS WITH NO SPECIFIED IMPEDANCE REQUIREMENT SHOULD BE BUILT TO INDICATED WIDTH.
 - APPLY LPI SOLDERMASK OVER BARE COPPER (SMOBC), COLOR: RED. SOLDERMASK SHALL CONFORM TO IPC-SM-840, CLASS H. CURRENT REV.
 - FABRICATION VENDOR IS ALLOWED TO INCREASE SOLDERMASK COMPONENT PADS BY A MAXIMUM 1 MIL ON EACH SIDE OVER THE COPPER PAD IN ORDER TO MEET TOOLING REQUIREMENTS WHILE MAINTAINING WEBBING BETWEEN ADJACENT PADS.
 - APPLY LPI SILKSCREEN OR EQUIVALENT PER THE ARTWORK BOTH SIDES. COLOR: WHITE.